

ABSTRACT

The present invention provides a method for forming a circuit having conductor lines arranged at fine pitches on a copper-clad laminate, which method solves a problem in that the thickness of a copper layer subjected to etching becomes thick as a result of plating for formation of plated through holes or via holes, to thereby easily form the circuit having conductor lines arranged at fine pitches. In manufacture of a double-sided printed wiring board or a multilayer printed wiring board having three or more layers, involving copper plating for establishing electrical interlayer continuity by means of plated through holes or via holes, a peelable-type copper foil with carrier foil having a peelable carrier foil is used in order to form an external layer of the printed wiring board. The printed wiring board is manufactured by the steps of forming through holes for formation of plated through holes or hole portions for formation of via holes without removal of the peelable carrier foil; performing desmearing and copper plating for establishing electrical interlayer continuity; peeling off the carrier foil; performing registration for an external circuit pattern on the external layer formed of the copper foil; and performing etching.